

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended): A magnetic head comprising:
 - a substrate;
 - a read head being fabricated upon said substrate;
 - a P1 pole being fabricated upon said read head;
 - a write gap layer being fabricated upon said P1 pole;
 - a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole tip includes a first sidewall portion being comprised of a seed layer and a second sidewall portion being comprised of electroplated material, and wherein said P2 pole tip has a thickness dimension t, and a base having a width dimension W;
 - and wherein said seed layer is comprised of an integrally formed layer of material that forms said base of said P2 pole tip and a said first sidewall of said P2 pole tip that extends throughout said thickness t of said P2 pole tip.
2. (currently amended): A magnetic head as described in claim 1 wherein said electroplated material that comprises said second portion of said P2 pole tip plated upon said seed layer material that forms a said first sidewall of said P2 pole tip.
3. (original): A magnetic head as described in claim 1 wherein said seed layer material is formed with a thickness of approximately 50 Å to approximately 500 Å, and said electroplated material is formed with a thickness of approximately 100 Å to approximately 5000 Å.

1 4. (original): A magnetic head as described in claim 3 wherein said seed layer material
2 thickness is approximately 250 Å and said electroplated material thickness is approximately
3 1500 Å.

1 5. (original): A magnetic head as described in claim 3 wherein said seed layer material is
2 comprised of NiFe and said electroplated material is comprised of NiFe.

1 6. (currently amended): A hard disk drive comprising:
2 at least one hard disk being fabricated for rotary motion upon a disk drive;
3 at least one magnetic head adapted to fly over said hard disk for writing data on said hard
4 disk, said magnetic head including:
5 a substrate;
6 a read head being fabricated upon said substrate;
7 a P1 pole being fabricated upon said read head;
8 a write gap layer being fabricated upon said P1 pole;
9 a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole
10 tip includes a first sidewall portion being comprised of a seed layer and a second sidewall portion
11 being comprised of electroplated material, and wherein said P2 pole tip has a thickness
12 dimension t, and a base having a width dimension W;
13 and wherein said seed layer is comprised of an integrally formed layer of material that
14 forms said base of said P2 pole tip and a said first sidewall of said P2 pole tip that extends
15 throughout said thickness t of said P2 pole tip.

1 7. (currently amended): A hard disk drive as described in claim 6 wherein said electroplated
2 material that comprises said second portion of said P2 pole tip plated upon said seed layer
3 material that forms a said first sidewall of said P2 pole tip.

1 8. (original): A hard disk drive as described in claim 6 wherein said seed layer material is
2 formed with a thickness of approximately 50 Å to approximately 500 Å, and said electroplated
3 material is formed with a thickness of approximately 100 Å to approximately 5000 Å.

1 9. (original): A hard disk drive as described in claim 8 wherein said seed layer material
2 thickness is approximately 250 Å and said electroplated material thickness is approximately
3 1500 Å.

1 10. (original): A hard disk drive as described in claim 8 wherein said seed layer material is
2 comprised of NiFe and said electroplated material is comprised of NiFe.

11-18 (withdrawn)

1 19. (currently amended): A magnetic head comprising:
2 a substrate;
3 a read head being fabricated upon said substrate;
4 a P1 pole being fabricated upon said read head;
5 a write gap layer being fabricated upon said P1 pole;

6 a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole
7 tip includes a base surface that is disposed upon said write gap layer and a first sidewall surface
8 that is disposed generally perpendicularly to said base surface, and wherein said base surface and
9 said first sidewall surface are comprised of an integrally formed layer of P2 pole tip seed layer
10 material;

11 and wherein said P2 pole tip includes an electroplated material portion, and wherein said
12 P2 pole tip includes a second sidewall surface that is disposed opposite to said first sidewall
13 surface, and wherein said second sidewall surface is comprised of said electroplated material.

1 20. (currently amended): A magnetic head as described in claim 19 wherein said base
2 surface defines a width W of said P2 pole tip and said first sidewall defines a thickness t of said
3 P2 pole tip.

1 21. (currently amended): A magnetic head as described in claim 20, ~~wherein said P2 pole tip~~
2 ~~further includes an electroplated material portion, and~~ wherein said electroplated material portion
3 is plated in part upon said first sidewall surface seed layer material.

1 22. (previously presented): A magnetic head as described in claim 21 wherein said seed
2 layer material is formed with a thickness of approximately 50 Å to approximately 500 Å, and
3 said electroplated material is formed with a thickness of approximately 100 Å to approximately
4 5000 Å.

1 23. (previously presented): A magnetic head as described in claim 21 wherein said seed layer
2 material thickness is approximately 250 Å and said electroplated material thickness is
3 approximately 1500 Å.

1 24. (previously presented): A magnetic head as described in claim 21 wherein said seed layer
2 material is comprised of NiFe and said electroplated material is comprised of NiFe.